Chromium Tolerant, Highly Active and Stable Electrocatalytic Internal Surface Coating for Cathode of Commercial SOFCs

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- Project Background & Technical Challenges
 - Alternative to an interconnect coating: Cr-resistant cathode through infiltration
 - ALD & technical challenges for the development of an ALD coated Cr-resistant cathode
- ALD-Enabled, Chromium Tolerant Air Electrode

L\$M/Y\$Z CATHODE

- LSM/YSZ: Baseline Performance & nanostructure degradation induced by Cr poisoning
- Cell power density & longevity increased by ALD coating
- ALD-enabled Significantly increased power density & durability against contamination

- Baseline nanostructure degradation induced by Cr poisoning
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Cr-Poisoning SOFC Cathode & Interconnect Coating

Commonly used metallic interconnect materials:

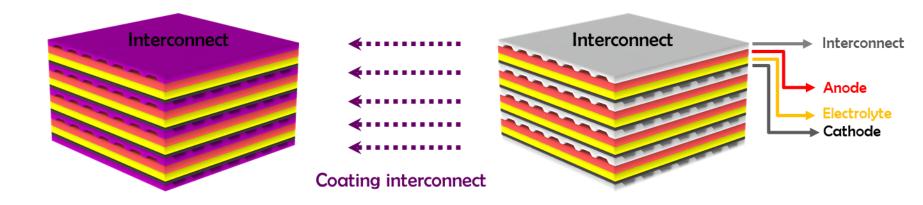
- Ni(Fe)-Cr based heat resistant alloys, Cr-based alloys, and chromia-forming ferric stainless steels.
- Contain Cr to form a protective chromium oxide scale Cr₂O₃.

Volatilization of Cr species strongly depends on oxygen partial pressure.

Vaporization of Cr species on the SOFC fuel side anode could be neglected.

Cr deposition & poisoning of SOFC cathode:

- Volatile Cr species, such as CrO₃ and Cr(OH)₂O₂, are generated in oxidizing atmospheres.
- Volatile Cr species react with the cathodes, causing rapid cell degradation.



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- Park, E.; Taniguchi, S.; Daio, T.; Chou, J. T.; Sasaki, K., Influence of cathode polarization on the chromium deposition near the cathode/electrolyte interface of SOFC. International Journal of Hydrogen Energy 2014, 39 (3), 1463-1475.

Development of Cr Tolerant Cathode via Infiltration or Coating

For commercial SOFC; with well-developed material; sets, Cathode Cr-resistance can be improved through solution-based infiltration or cathode surface coating.

<u>Structural</u> requirements of Cr-tolerant surface coating layer on SOFC cathode:

- Deeply penetrating into the active layer of the cathode.
- <u>Uniform and conformal</u> on the internal surface of the cathode active layer that possess complex three-dimensional topographies with high aspect ratio, <u>and the TPBs</u>.
- Intimate adhesion and bonding to the cathode surface at atomic scale without spallation.

Coating Film deposition to facilitate the Cr-tolerant cathode through coating: Magnetron sputtering, sol-gel dip-coating, and electro-deposition techniques used for applying protective coating on ferritic stainless steel interconnects:

- Involving physical vapor deposition or liquid solutions.
- Having the limitation of not deeply penetrating into the cathode active layer or not providing the conformal coating on cathode surface.
- Not ideal for infiltrating and coating the internal surface of porous cathode.

Atomic Layer Deposition: Chemical vapor deposition technique that sequentially applied atomic mono-layers to a substrate, typically alternating compounds to produce a locally balanced atomic distribution of target material.

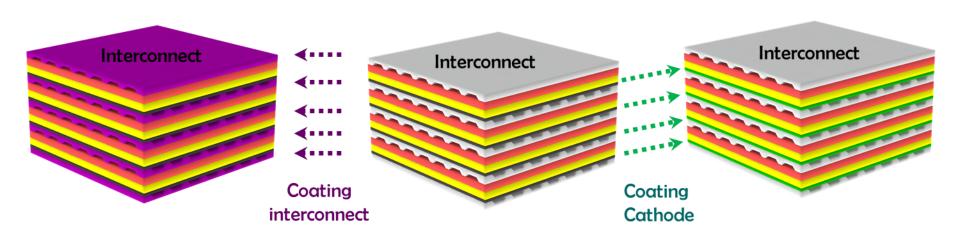
ALD is uniquely suitable for coating uniform and conformal films on complex three-dimensional topographies with high aspect ratio.

Development of Cr Tolerant Cathode Through ALD Coating

For a commercial SOFC with well-developed materials set, Cathode Cr-resistance can be improved through ALD coating.

ALD is uniquely suitable for depositing uniform and conformal films on complex three-dimensional topographies with high aspect ratio.

Two Alternative Approaches to Mitigate Cr Poisoning



Approach I **Interconnect Coating**

Approach II **ALD Coating of Cathode**

Technical challenges for ALD coating of Cr resistance layers

<u>Structure</u> requirement of Cr-tolerant surface coating could be satisfied by ALD:

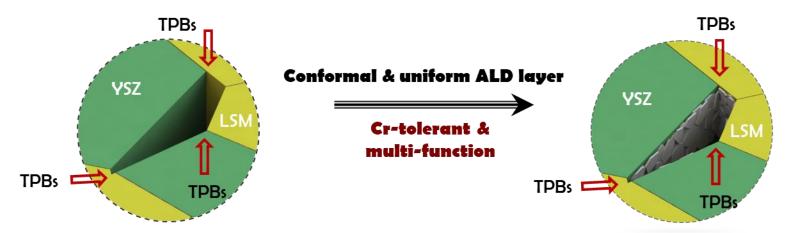
- ☑ <u>Deeply penetrating</u> into the active layer of the cathode.
- ☑ <u>Uniform and conformal</u> on the internal surface of the cathode active layer, that possess complex three-dimensional topographies with high aspect ratio, and the TPBs.
- ☑ Intimate adhesion and bonding to the cathode surface at atomic scale without spallation.

<u>Functional</u> requirement of Cr-tolerant surface coating layer on SOFC cathode:

 Cr-inert ALD coating layer should not impair the electrochemical reactions taking place on the cathode surface.

Ideal Cr-inert ALD coating layer should possess the multiple functions of:

- Conformal on internal surfaces of backbones, prevent Sr out diffusion and Cr inward diffusion.
- Highly active towards electrochemical reactions.
- Super stable upon the long term electrochemical operation at high temperatures.



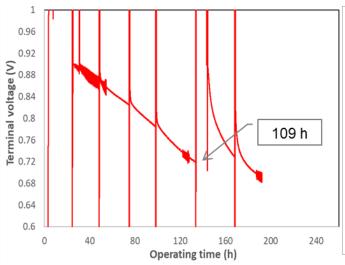
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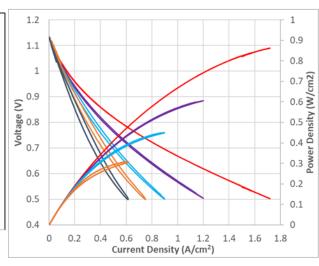
L\$M/Y\$Z CATHODE

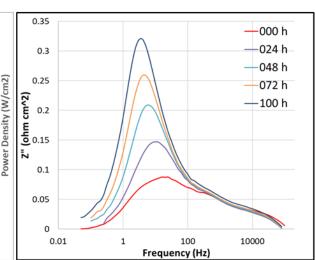
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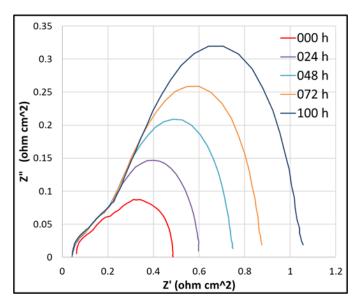
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Severe Degradation of LSM/SSZ Baseline Cell Upon Cr Contamination









Operating time (h)	Peak power density (W/cm²)	Percentage degradation (%)
0	0.862	-
24	0.605	29.8 %
50	0.45	47.8 %
74	0.375	56.5 %
109	0.307	64.4 %

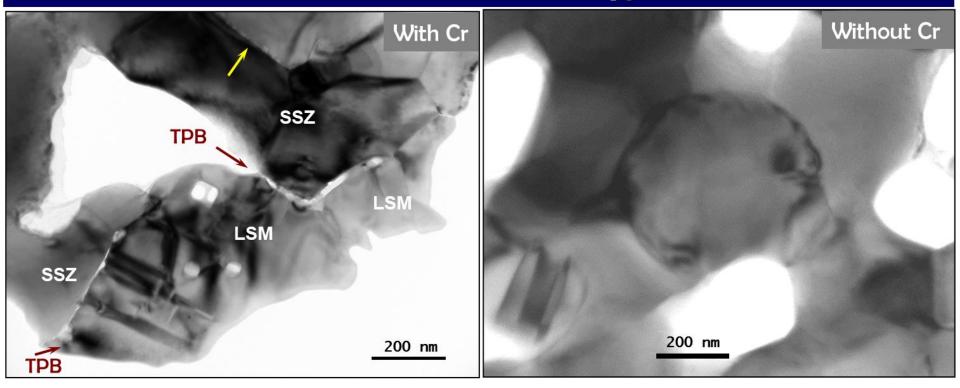
100 h operation, the terminal voltage dropped ~ 190 mV.

At 0.3 A/cm²; Degradation rate is 1.68 V per 1000 h

Severe Degradation of LSM-based Baseline Cell

- Little change of series resistance R_s.
- Large increase of the polarization resistance R_p.
- R_p increase could be related to activity loss of oxygen reduction reaction at TPB.

As-Received LSM Baseline Cell Cathode: Typical Nanostructure



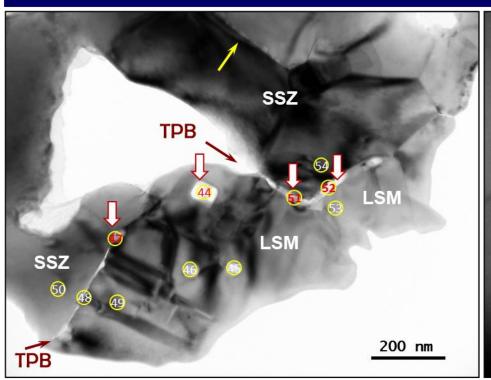
Baseline without Cr contamination.

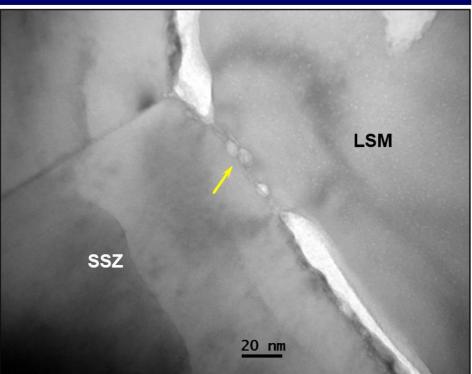
- Intact clean LSM/YSZ interface.
- No formation of the nano-scale MnO_x, SrO_x, or La₂O₃ phases.

Başeline with Cr contamination: Original TPB and L\$M/\$\$Z Interface Degradation.

- Internal cracking initiated from the original triple phase boundary (TPB) and propagated along the internal interface between Sc-stabilized ZrO₂ (SSZ) and LSM.
- In the local SSZ/LSM interface region that there is no apparent internal cracking, there are internal nano-pores that are elongated along the SSZ/LSM interface.
- Intragranular structure has spherical nano-pores, while the SSZ grains remained to be intact.

Cr Contamination: Nanostructure Degradation of LSM/SSZ Baseline Cell

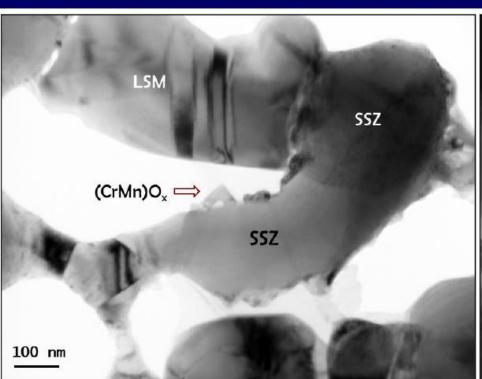


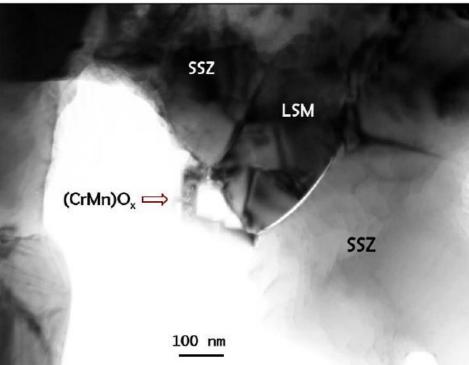


Atomic%	0	La	\$r	Mn	Zr	\$c	Cr	Formulation
44	66.37	12	3.1	15.14		V	3.39	Lao. ₇₉ Sro. ₂₁ MnCr _{o.22} O _x
45	71.89	10.37	2.53	14.76			0.46	$La_{0.8}Sr_{0.2}Mn_{1.14}Cr_{0.04}O_{x}$
46	68.01	11.99	3.23	16.65			0.12	LaSrMn _{0.97} Cr _{1.06} O _x
47	73.06	7.35		7.15	3.85	0.79	7.8	$LaSrMn_{0.97}Cr_{1.06}O_x + ZrO_2$ (w 10 % Sc_2O_3)
48	69.81	2.76		3.45	19.29	3.48	1.21	LaSrMn _{1,25} Cr _{,44} O _x + ZrO ₂ (w 9 % Sc ₂ O ₃)
49	71.34	10.66	2.69	15.31				La.8Sr.2Mn1.15Ox
50	63.35			0.82	29.84	6		ZrO2 (w 9 % Sc ₂ O ₃) +Mn.O3
51	70.96	2.7		4.14	7.43	1.75	13.04	CrOx enriched
52	76.77	2.73		2.94	12.46		5.11	CrOx enriched
53	73.19	9.96	2.44	12.78			1.63	$La_{.8}Sr_{.2}Mn_{1.03}Cr_{.13}O_{x}$
54	66.96			0.96	27.55	4.54		

Doped ZrO₂ and L\$M interface also show nano-pores.

Cr Contamination: Nanostructure Degradation of LSM/SSZ Baseline Cell





Original TPB Degradation & Formation of (CrMn)O $_{\rm x}$ on \$\$Z grain surfaces

- Additional (CrMn)O_x enriched crystals appear to nucleated at the original TPBs.
- Additional (CrMn)O_x enriched crystals appear to grown on SSZ grain surfaces.

Applying an ALD coating layer on the internal surface of cathode: Ideal Cr-inert should possess the multi-functionality of:

- Fully conformal to prevent Sr outward diffusion and prevent Cr inward diffusion.
- Highly active towards electrochemical reactions.
- Super stable upon the electrochemical operation at elevated temperatures.

<u>Choice of Cr tolerance ALD Layer:</u> $Mn_{0.8}Co_{0.2}O_x$ is ordinary interconnect coating materials, excellent layer to **prevent** Cr penetration.

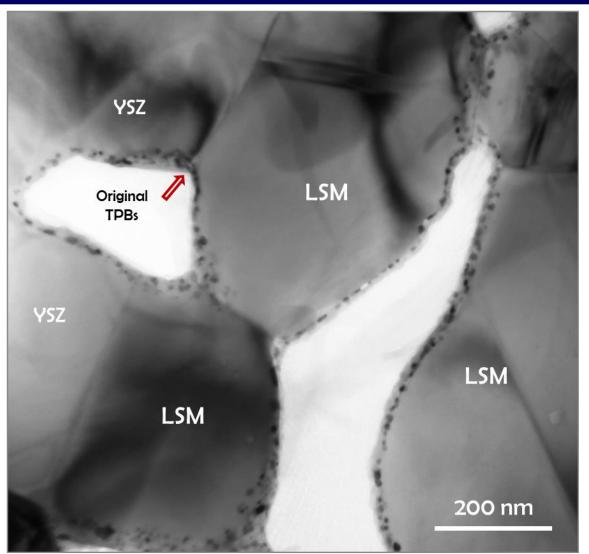
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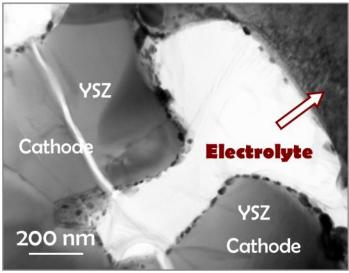
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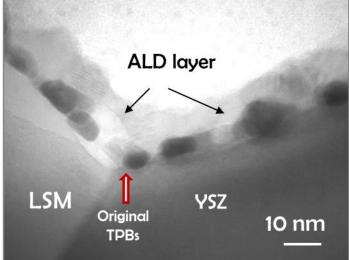
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Structure Requirement for ALD Layer: Fully Conformal and Uniform



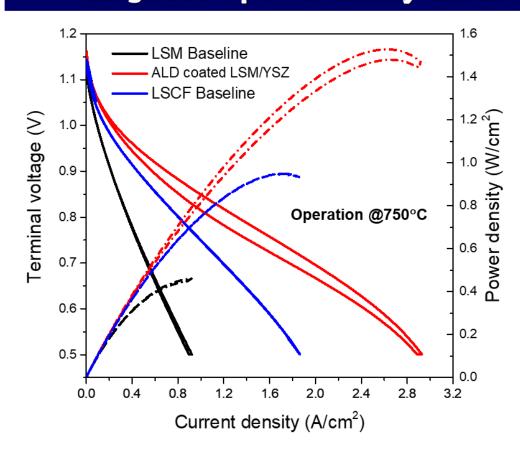


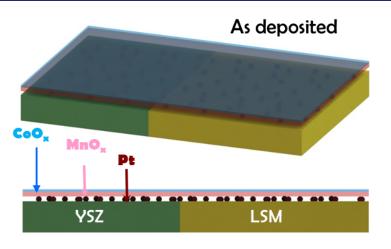


After operation at 750C for 120 hours:

- Stable nanostructure at ALD layer are at active layer and at the cathode-electrolyte interface.
- Conformal & uniform; ALD layer is with nano-pores for gas penetration; Covering the original TPBs.

Structural Requirement for ALD Layer: Enhancement Cell Performance Large 380% power density enhancement of commercial SOFCs



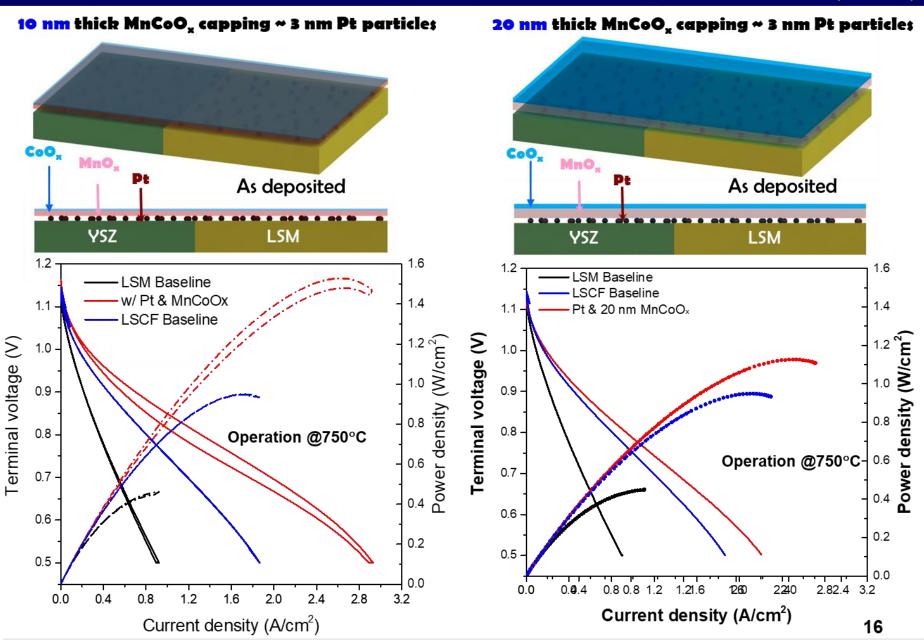


ALD coated L3M/Y3Z cell:

- power density is 380% of that from the LSM/YSZ baseline at 750°C.
- power density is 170% of that from the LSCF/SDC baseline at 750°C.

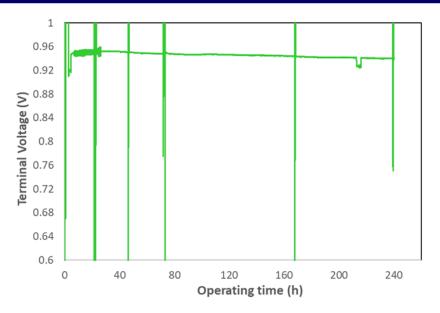
Surface architecture	$R_{ m total} \ (\Omega/{ m cm}^2)$	R_{s} (Ω/cm^{2})	$R_{\rm p}$ $(\Omega/{ m cm}^2)$	/at 0.8 V (A/cm²)	P at 0.8 V (W/cm²)	Factor enhancement to LSM/YSZ	Factor enhancement to LSCF/SDC
LSM/YSZ Baseline	0.619	0.045	0.574	0.350	0.28	1	1
ALD LSM/YSZ	0.324	0.051	0.273	1.320	1.06	380%	170%
LSCF/SDC Baseline	0.350	0.110	0.239	0.790	0.63	1	1

Tuning the Cell Performance by Adjusting ALD Layer Thickness (no Cr)



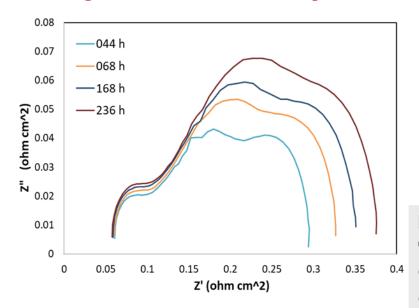
10 nm ALD layer, peak power density is 380% of baseline. 20 nm ALD layer, peal power density is 280 % of baseline.

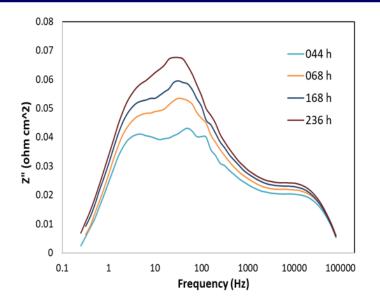
Stable Performance of ALD Coated Cell Upon Operation With Cr



ALD coated LSM based cell at 0.3 A/cm²

Degradation rate is 0.054 V per 1000 h





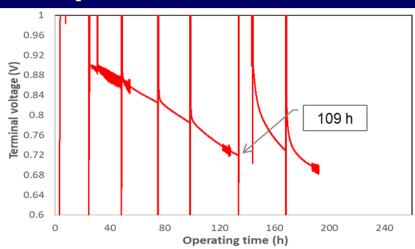
Rs and Rp (taken at 0.3 A/cm²) changes

Operating time (h)	Rs $(\Omega \ { m cm^2})$	Rp (Ω cm ²)
44	0.06	0.304
68	0.058	0.328
168	0.058	0.354
236	0.055	0.381

LSM/YSZ with ALD coating of 20 nm ${\rm Mn_{0.8}Co_{0.2}O_x}$ layer, operation with Cr contamination.

- Zero hour: peak power density is 280 % of baseline @ zero hour;
- 168 hours: peak power density is 200 % of baseline @ zero hour.

Comparison of Baseline & ALD Coated Cells Upon Cr Contamination

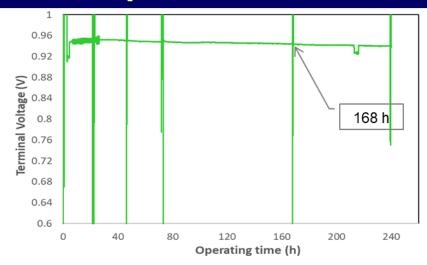


LSM based Baseline Cell:

baseline at 0.3 A/cm²

Degradation rate is 1.68 V per 1000 h

Operating	Peak power	Percentage
time	density	degradation
(h)	(W/cm²)	(%)
0	0.862	-
24	0.605	29.8 %
50	0.45	47.8 %
74	0.375	56.5 %
109	0.307	64.4 %



ALD Coated Cell LSM Based Cells ALD coated cell at 0.3 A/cm² Degradation rate is 0.054 V per 1000 h

Operating time (h)	Peak power density (W/cm²)	Percentage degradation (%)
23	1.254	-
44	1.127	0.101276
68	1.073	0.144338
168	1.015	0.19059

Baseline Cells Peak power density remained to be 36% of baseline @ zero hour after 109 hours operation.

ALD coated one: Peak power density remained to be 200% of uncoated baseline @ zero hour after 168 hours operation. ALD coated cell power density is ~ 600% of that baseline cell upon operation with Cr contamination.

<u>Cr tolerances</u> Large performance enhancement (> 200% power density) by ALD coating of Cr-tolerant $Mn_{0.8}Co_{0.2}O_x$ and remained to be stable even operation with Cr contamination.

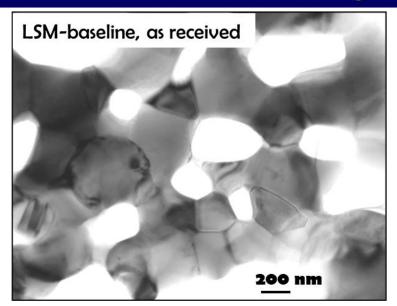
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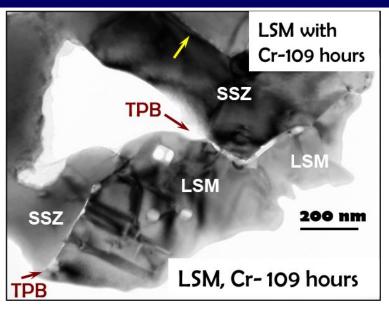
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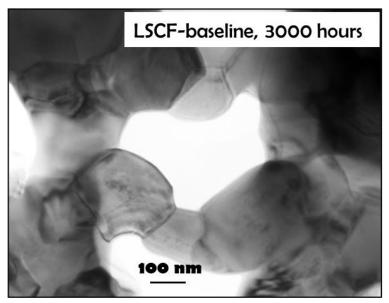
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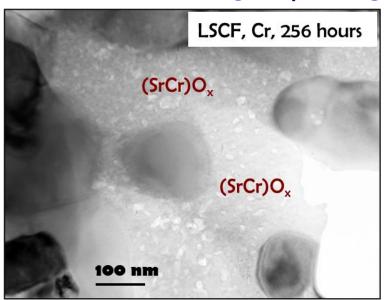
Cr contamination: Different Degradation between LSM and LSCF based Cells





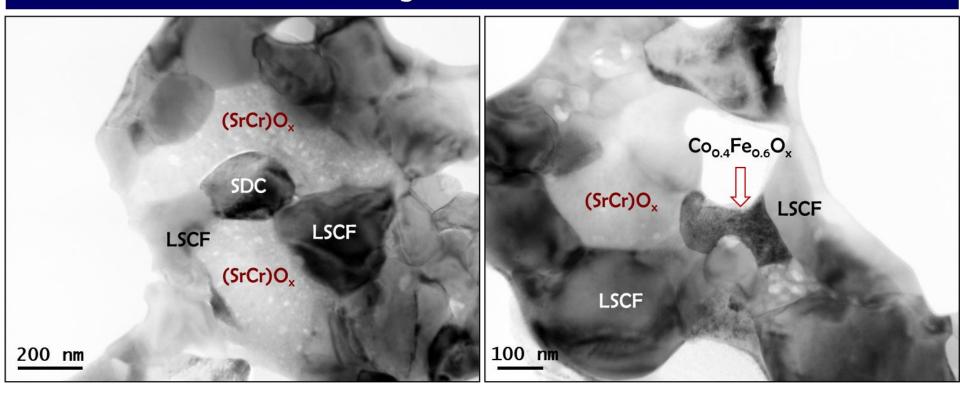
LSM: Cr is attacking the TPB. No accumulation at the original pore region.





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Cr contamination: Different Degradation Mechanisms from LSM & LSCF Cells



Accelerated Sr segregation induced by Cr contamination

LSCF-SDC cathode nanostructure degradation caused by Cr-contamination.

- (SrCr)O $_{\rm x}$ are filling the original pores of the LSCF/SDC after 256 hours operation at 750°C.
- Formation of (FeCo)Ox nano-grains at LSCF/LSCF surface grain boundaries.

ALD layer on LSCF/SDC backbone ideally needs to be conformal to prevent the Sr evaporation/Segregation and their further interaction with Cr vapors.



LSM/YSZ or LSM/SSZ based cells:

- LSM/SSZ baseline performance & nanostructure degradation by Cr
 - Peak power density loss of 64% after 109 hours operation. Dramatic increase in R_p.
 - Cracking at LSM/SSZ interface, LSM grains. SSZ remains intact, but with (CrMn)O_x.
- > ALD coating (MnCo)O_x/Pt dramatically improves the Cr resistance
 - Power density is 280-380% of the baseline cell depending on the ALD layer thickness.
 - For cell with a 20 nm thick ALD layer, there is a large performance enhancement (> 200% power density) induced by ALD coating of Cr-tolerant Mn_{0.8}Co_{0.2}O_x.
 - For cell with 20 nm thick ALD layer, after 168 hours at 750°C power density of ALD-coated cell is ~ 600% of that baseline cell upon operation with Cr contamination for 109 hours.

LSCF/SDC cells:

- LSCF/SDC baseline performance & nanostructure degradation by Cr
 - With the Cr source, there is no apparent Sr surface segregation phase even for the baseline cell operated for 3000 hours at 750°C.
 - With the Cr source, there is significant amorphous (SrCr)O_x phase accumulated in the original pore region.
 - There is completely different nanostructure degradation mechanisms between LSM and LSCF cells induced by Cr contamination.
 - LSCF based cells ideally need the conformal ALD layer to prevent Sr migration and Cr contamination.

ACKNOWLEDGEMENTS

DOE-SOFC Program

National Energy Technology Laboratory

Program Manager: Dr. Joseph Stoffa

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